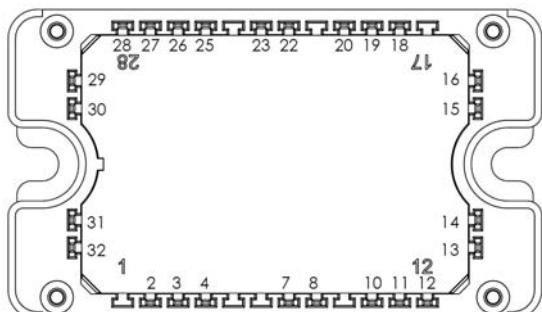
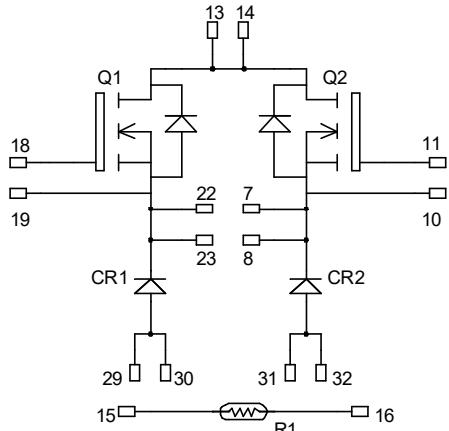


*Dual buck chopper
Super Junction MOSFET
Power Module*

V_{DSS} = 600V
R_{DSon} = 24mΩ max @ T_j = 25°C
I_D = 95A @ T_c = 25°C



All multiple inputs and outputs must be shorted together

Example: 13/14 ; 29/30 ; 22/23 ...

All ratings @ T_j = 25°C unless otherwise specified

Absolute maximum ratings (per super junction MOSFET)

Symbol	Parameter		Max ratings	Unit
V _{DSS}	Drain - Source Voltage		600	V
I _D	Continuous Drain Current	T _c = 25°C	95	A
		T _c = 80°C	70	
I _{DM}	Pulsed Drain current		260	
V _{GS}	Gate - Source Voltage		±20	V
R _{DSon}	Drain - Source ON Resistance		24	mΩ
P _D	Power Dissipation	T _c = 25°C	462	W
I _{AR}	Avalanche current (repetitive and non repetitive)		15	A
E _{AR}	Repetitive Avalanche Energy		3	mJ
E _{AS}	Single Pulse Avalanche Energy		1900	

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Electrical Characteristics (per super junction MOSFET)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} = 0V, V _{DS} = 600V			350	µA
R _{DS(on)}	Drain – Source on Resistance	V _{GS} = 10V, I _D = 47.5A			24	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = 5mA	2.1	3	3.9	V
I _{GSS}	Gate – Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0V			200	nA

Dynamic Characteristics (per super junction MOSFET)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C _{iss}	Input Capacitance	V _{GS} = 0V ; V _{DS} = 25V f = 1MHz		14.4		nF
C _{oss}	Output Capacitance			17		
Q _g	Total gate Charge	V _{GS} = 10V V _{Bus} = 300V I _D = 95A		300		nC
Q _{gs}	Gate – Source Charge			68		
Q _{gd}	Gate – Drain Charge			102		
T _{d(on)}	Turn-on Delay Time	Inductive Switching (125°C) V _{GS} = 10V V _{Bus} = 400V I _D = 95A R _G = 2.5Ω		21		ns
T _r	Rise Time			30		
T _{d(off)}	Turn-off Delay Time			100		
T _f	Fall Time			45		
E _{on}	Turn-on Switching Energy	Inductive switching @ 25°C V _{GS} = 10V ; V _{Bus} = 400V I _D = 95A ; R _G = 2.5Ω		1350		µJ
E _{off}	Turn-off Switching Energy			1040		
E _{on}	Turn-on Switching Energy	Inductive switching @ 125°C V _{GS} = 10V ; V _{Bus} = 400V I _D = 95A ; R _G = 2.5Ω		2200		µJ
E _{off}	Turn-off Switching Energy			1270		
R _{thJC}	Junction to Case Thermal Resistance				0.27	°C/W

Chopper diode ratings and characteristics (per diode)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V _{RRM}	Peak Repetitive Reverse Voltage				600	V
I _{RM}	Reverse Leakage Current	V _R =600V			100	µA
I _F	DC Forward Current		T _c = 80°C	100		A
V _F	Diode Forward Voltage	I _F = 100A		1.6	2	V
		I _F = 200A		2		
		I _F = 100A	T _j = 125°C	1.3		
t _{rr}	Reverse Recovery Time	I _F = 100A V _R = 400V di/dt=200A/µs	T _j = 25°C	160		ns
			T _j = 125°C	220		
Q _{rr}	Reverse Recovery Charge	I _F = 100A V _R = 400V di/dt=200A/µs	T _j = 25°C	290		nC
			T _j = 125°C	1530		
R _{thJC}	Junction to Case Thermal Resistance				0.55	°C/W

Thermal and package characteristics

Symbol	Characteristic	Min	Max	Unit		
V _{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz	4000		V		
T _J	Operating junction temperature range	-40	150			
T _{JOP}	Recommended junction temperature under switching conditions	-40	T _{jmax} -25	°C		
T _{STG}	Storage Temperature Range	-40	125			
T _C	Operating Case Temperature	-40	125			
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package Weight			110	g	

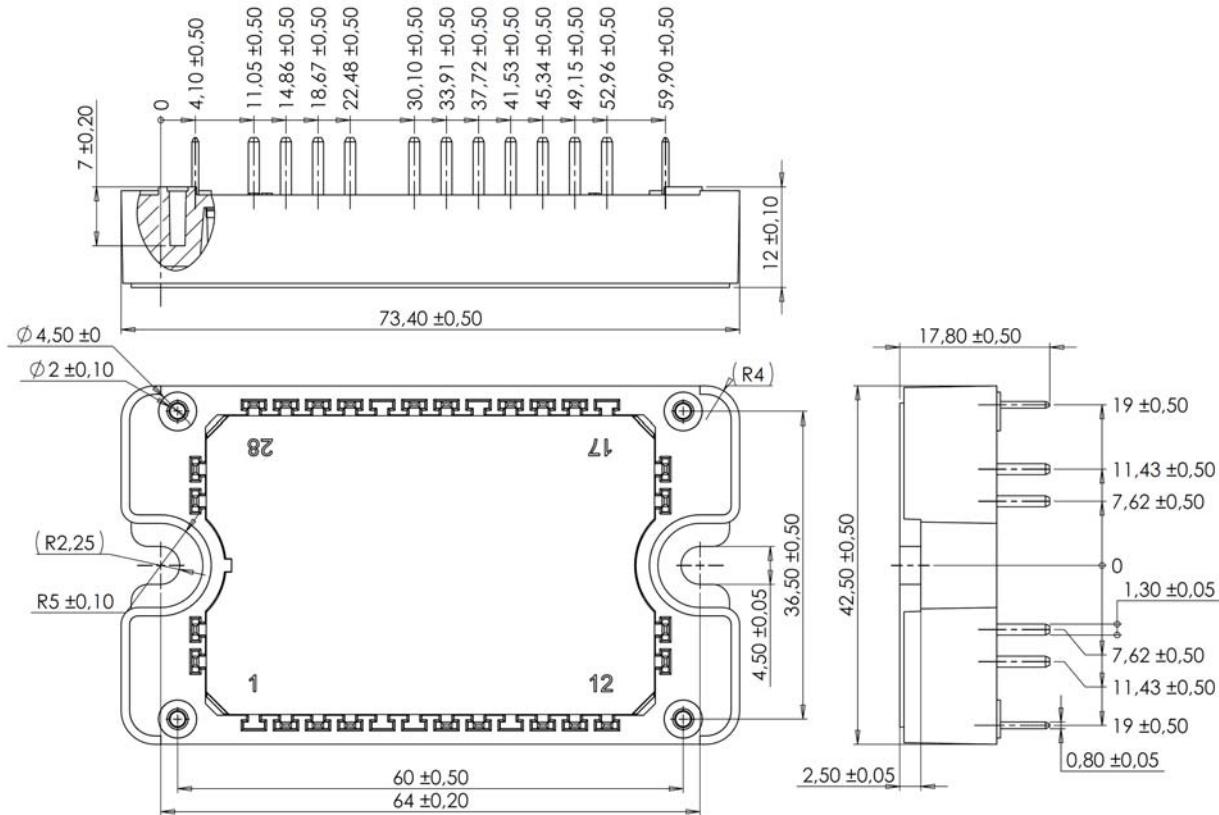
Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C		50		kΩ
ΔR ₂₅ /R ₂₅			5		%
B _{25/85}	T ₂₅ = 298.15 K		3952		K
ΔB/B		T _C = 100°C	4		%

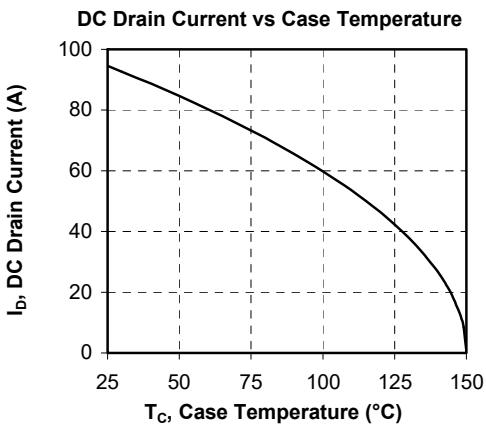
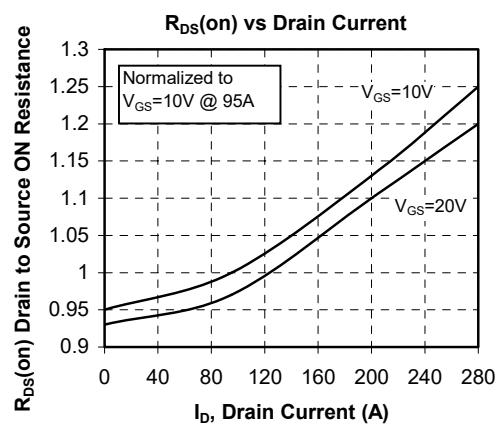
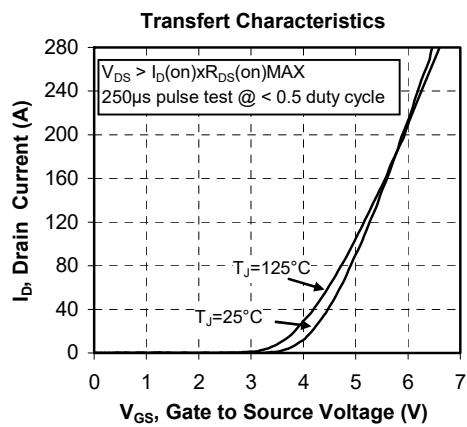
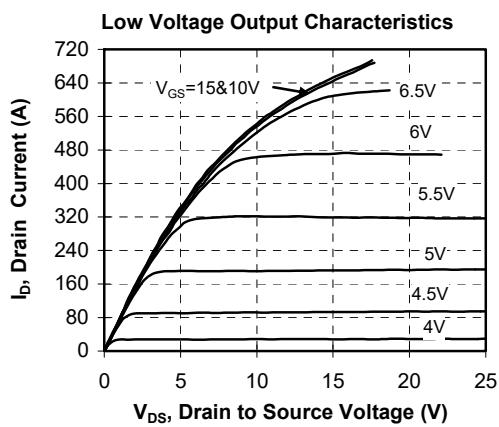
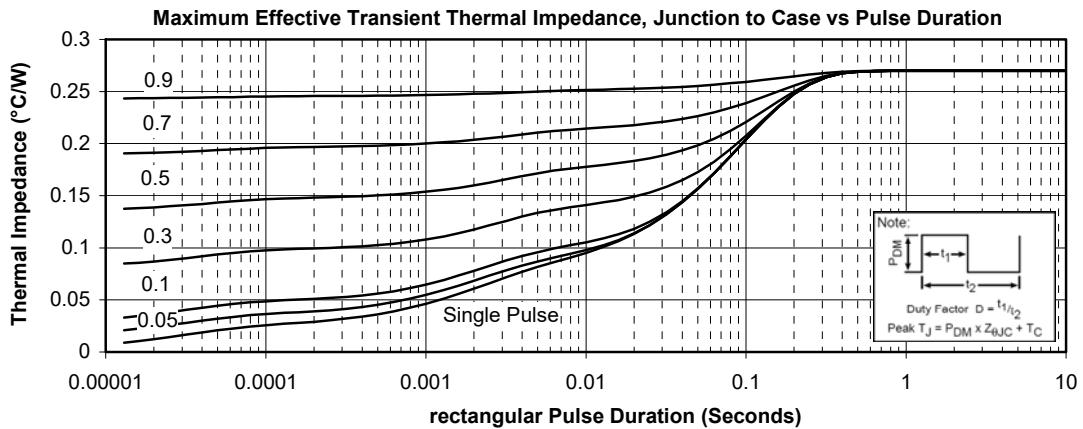
$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

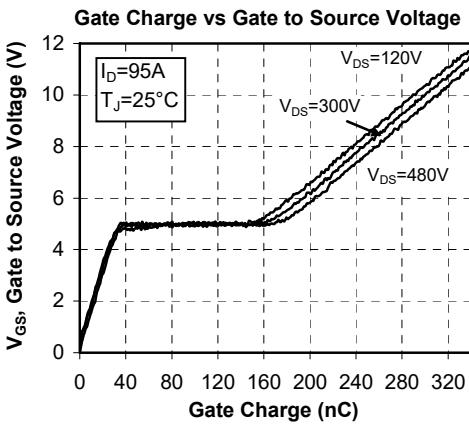
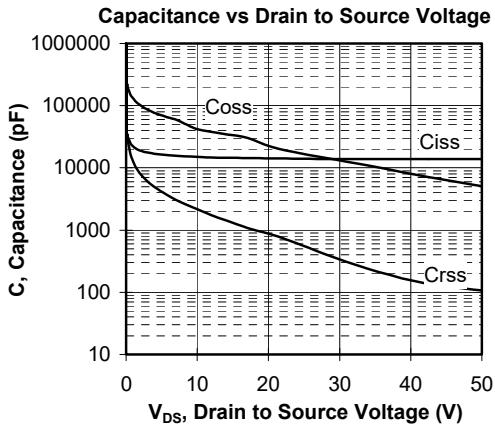
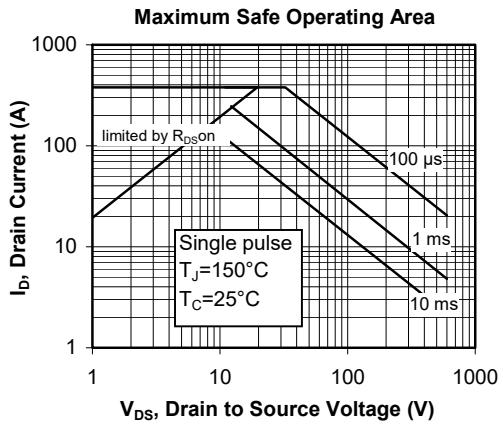
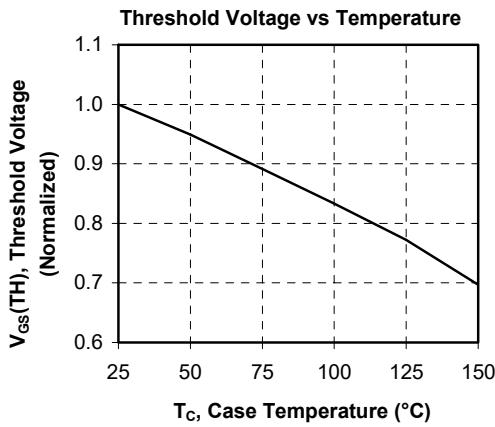
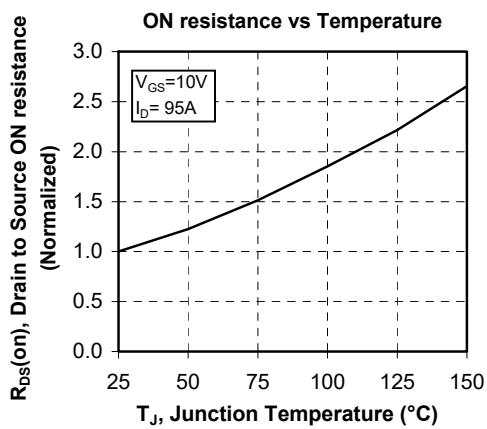
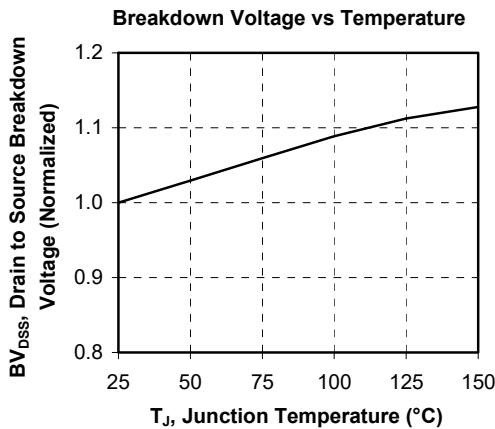
T: Thermistor temperature
R_T: Thermistor value at T

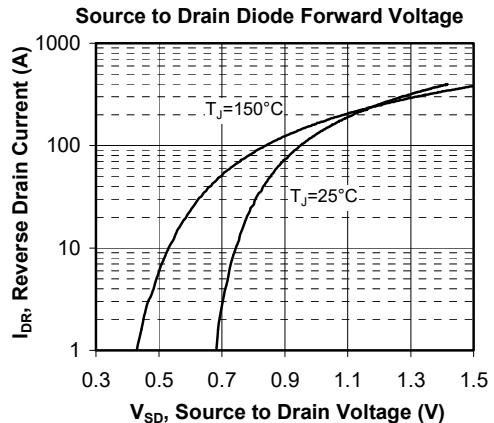
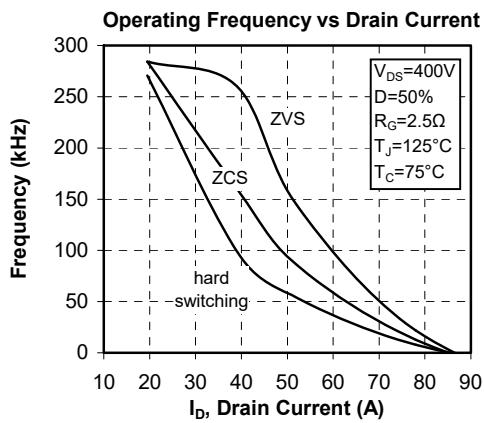
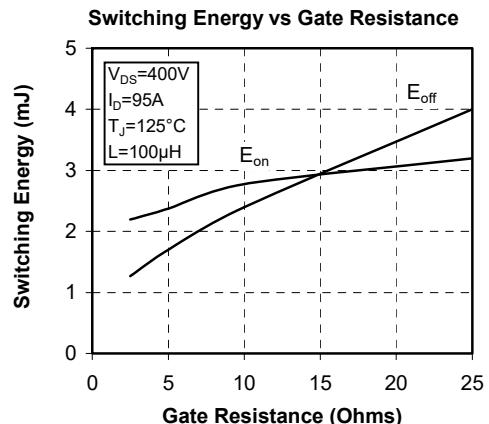
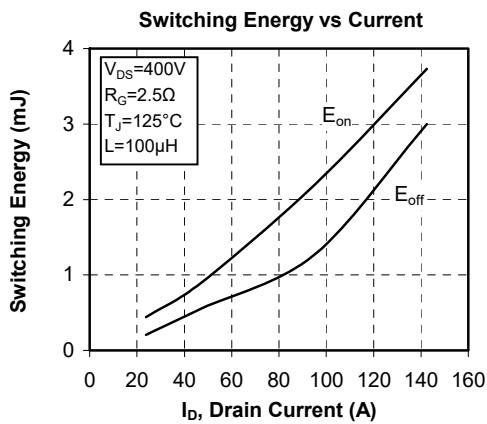
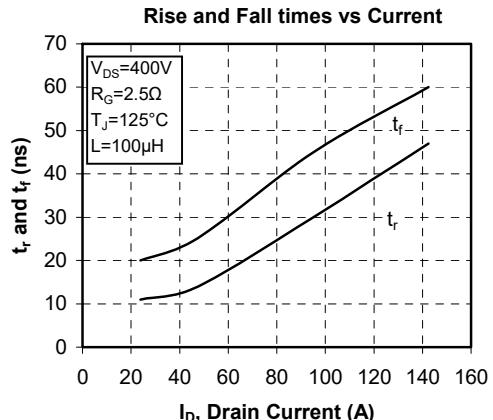
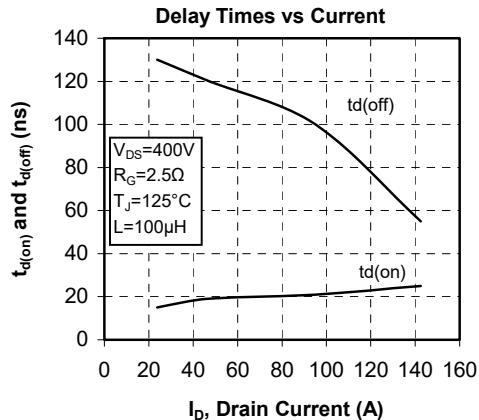
Package outline (dimensions in mm)



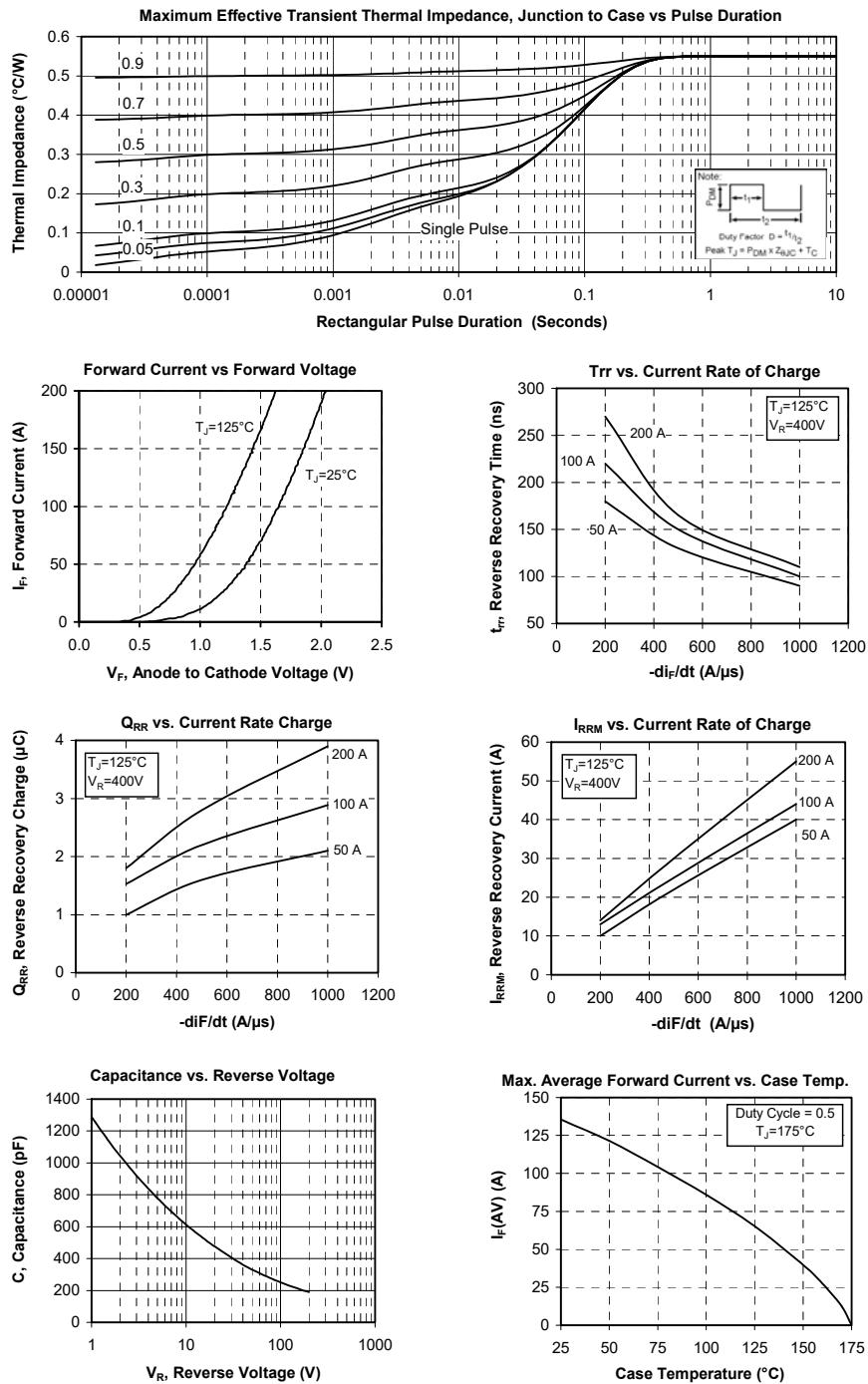
See application note 1906 - Mounting Instructions for SP3F Power Modules on www.microsemi.com

Typical Super junction MOSFET Performance Curve






Typical chopper diode performance curve



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